



SOT500-4

plastic leadless module carrier package; 35 mm wide tape

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	PLLMC
Package type industry code	PLLMC
Package style descriptive code	PLLMC (plastic leadless module carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	18-2-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.95	-	35	35.05	mm
A	seated height	[tbd]	-	[tbd]	0.26	mm
n ₂	actual quantity of termination	-	-	0	-	



2. Package outline

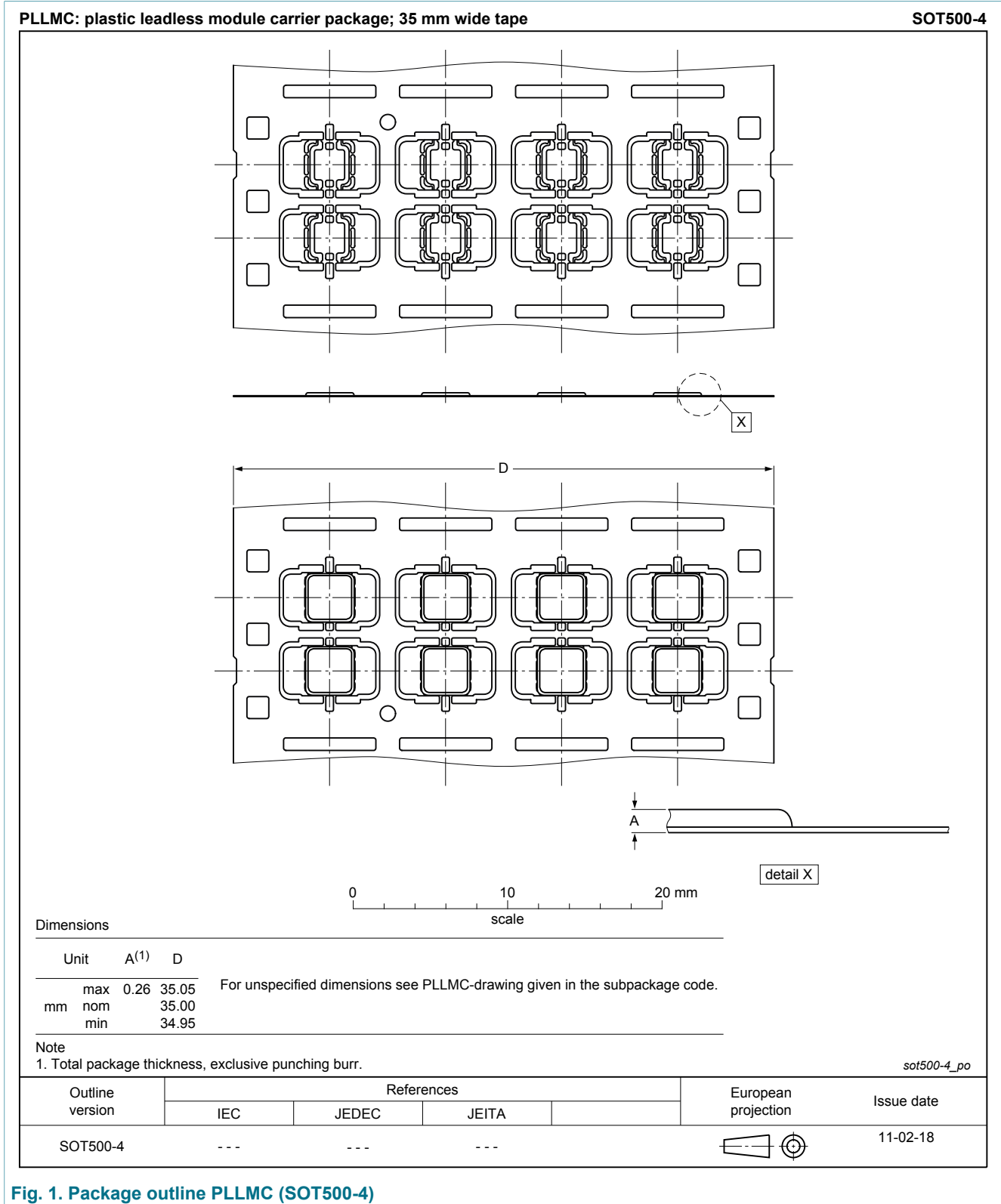


Fig. 1. Package outline PLLMC (SOT500-4)

3. Legal information

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